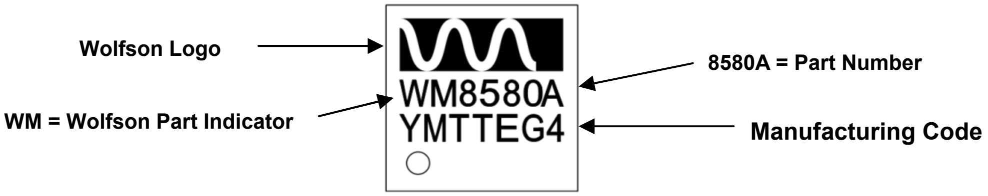
Product Order Codes



For ordering products, the name is specified according to the following convention:
WMFFxxCafv-zzetpddd/RVK

WM	Wolfson part indicator	
FFxxa	Family Part Number (a = Optional character to differentiate between base designs)	
C	Optional Copper bonding wire identifier	
fv	Optional Functional Differentiator	
-zz	Optional Speed, Voltage or Performance Indicator,	
e	Environmental Package & Plating:	
	S	Lead Free, green mold compound for all parts manufactured after 2007 Lead Free, might not be green mold compound for parts manufactured before 2007
	G	Lead Free, green mold compound
t	Temperature Grade	
p	Package	
ddd	(optional) OTP program identifier	
/R	(optional) 13” Tape and Reel supply	
/V	(optional) Dry Baked and Vacuum Packed supply	
/K	(optional) Customer packing identifier	

The manufacturing code is specified according to the following convention: YMTTMMM.
This is decoded as:
Y = Year – Last digit of year (e.g. 2010 will be represented by 0).
M = Month – In the sequence Jan = 1, Feb = 2…Sept = 9, Oct = A, Nov = B, Dec = C.
TT = Lot Trace Code. AA to ZZ, starts with AA, increments for each batch
MMM = Unique code for identification of Wafer Fab, Assembly Site and Die Version

Product Order Codes

Temperature Decoding Options:

C	Commercial 0° - 70°C
I	Industrial -40°C – 85°C
M	Military -55°C - 125°C
E	Extended (any other range specified by application)

Package Decoding Options:

C	Ceramic Dual-In-Line (CerDIP)
P	8 Pin Plastic Dual-In-Line (PDIP)
N	> 8 Pins Plastic Dual-In-Line (PDIP)
D	8 to 16 Pins Plastic Small-Outline IC, 0.15" Wide Narrow Body (SOIC)
DW	16 to 28 Pins Wide Body Plastic Small-Outline IC, 0.3" Wide Body (SOICW)
DC	Ceramic SOIC
DS	Plastic Shrink Small Outline Package (SSOP)
DT	Plastic Thin Shrink Small Outline Package (TSSOP)
J	Ceramic J-lead Chip Carrier (CJCC)
LC	Ceramic Leadless Chip Carrier (CLCC)
FN	Plastic J-lead Chip Carrier (PLCC)
G	Ceramic Pin-Grid Array (PGA)
B	Ball Grid Array (BGA)
FK	Quad Flat Pack No Leads (QFN) (0.6mm package height)
FL	Quad Flat Pack No Leads (QFN) (0.75mm/0.9mm package height)
FR	Regular Quad Flat Pack Styles (QFP)
FT	Thin Quad Flat Pack Styles (QFP)
FC	Ceramic Quad Flat pack (CERQUAD)
Y	Un-packaged. In die form only, supplied in die trays
W	Wafer Form
CN	Chip-On-Leadframe QFN Package (0.6mm max package height)
CO	Chip-On-Leadframe QFN Package (0.75mm/0.9mm package height)
CS	Wafer Level Chip Scale Package (WCSP)
CSN	Wafer Level Chip Scale Package – Non Backside Coat (WCSP)
MS	MEMS Package (Standard)
MSE	MEMS Package (Standard Enhanced)
MH	MEMS Package (High Performance)
MHE	MEMS Package (High Performance Enhanced)